

CY8CKIT-148 PSoC® 4700S Inductive Sensing Evaluation Kit Release Notes

Release Date: November 23, 2018

Thank you for your interest in the CY8CKIT-148 PSoC® 4700S Inductive Sensing Evaluation Kit. This document lists kit contents, installation requirements, kit documentation, limitations, and known issues.

Kit Contents

The CY8CKIT-148 PSoC 4700S Inductive Sensing Evaluation Kit includes the following:

- CY8CKIT-148 PSoC 4700S Inductive Sensing Evaluation board
- Metal Target
- USB Type-A to Type-C Cable
- Quick Start Guide

Software and Tools

The code examples shipped with this kit require PSoC Creator™ 4.2 or later. This is available with the kit installer or on the PSoC Creator webpage (www.cypress.com/psoccreator).

PSoC Programmer 3.27.1 or later and KitProg2 v1.05 or later are required to program the PSoC 4700S device on the PSoC 4700S Evaluation Kit. PSoC Creator installer or the kit installer automatically installs PSoC Programmer and KitProg2 drivers.

Install the PSoC 4700S device and latest MagSense™ component using PSoC Creator 4.2 or later. For more information, please refer to the kit guide.

Code Examples and Kit Collateral

The CY8CKIT-148 PSoC 4700S Inductive Sensing Evaluation Kit webpage is www.cypress.com/CY8CKIT-148. The webpage includes the kit installation packages, DVD image (ISO), and setup files (EXE) to install the code examples, documents, and hardware files of this kit.

Installation

Installation instructions are provided in the CY8CKIT-148 PSoC 4700S Inductive Sensing Evaluation Kit Guide, which is available at www.cypress.com/CY8CKIT-148.

Kit Revision

This is Rev. *A of the CY8CKIT-148 PSoC 4700S Inductive Sensing Evaluation Kit. The code example shipped with the kit is updated to make touch detection over metal overlays more robust.

Limitations and Known Issues

The following are the limitations and known issues in this revision of CY8CKIT-148 PSoC 4700S Inductive Sensing Evaluation Kit.

 Issue: When the kit is in CMSIS-DAP programming mode, this kit also enumerates as a Mass Storage programmer, however programming the PSoC 4700S device in Mass Storage mode is not supported.

Workaround: Use CMSIS-DAP mode for program and debug operation.

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For limitations and known issues with the PSoC 4700S silicon, refer to the PSoC 4700S datasheet.

Documentation

The kit documents are located in the Documentation folder, in the installation directory. The default location for the kit documents is:

<Install_Directory>\CY8CKIT-148 PSoC 4700S Inductive Sensing Evaluation Kit\<version>\Documentation

Documents include:

- CY8CKIT-148_Kit_Guide.pdf
- CY8CKIT-148 Quick Start Guide.pdf
- CY8CKIT-148 Release Notes.pdf

After opening PSoC Creator, on the Start Page, select **Start > Kits > CY8CKIT-148** for links to the kit documentation on the right panel. Expand **CY8CKIT-148** for kit code examples.

Additional tool and device documentation is available in **Help > Documentation**.

Technical Support

For assistance, go to www.cypress.com/support or contact our customer support at +1 (800) 541-4736 Ext. 3 (in the USA), or +1 (408) 943-2600 Ext. 3 (International).

Additional Information

- For more information about PSoC Creator functionality and releases, visit the PSoC Creator webpage: www.cypress.com/psoccreator.
- For more information about PSoC Programmer and supported hardware, visit the PSoC Programmer webpage: www.cypress.com/psocprogrammer.
- For a list of trainings on PSoC Creator, visit www.cypress.com/go/creatorstart/creatortraining.

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